

S/N 09/640961



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Qing Ma et al.	Examiner:	Sheila Clark
Serial No.:	09/640961	Group Art Unit:	2815
Filed:	August 16, 2000	Docket No.:	884.792US1
Title:	DIRECT BUILD-UP LAYER ON AN ENCAPSULATED DIE PACKAGE		
Assignee:	Intel Corporation		

#21/E

AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Applicants have reviewed the Office Action mailed on March 13, 2003. Please amend the above-identified patent application as follows.

PRELIMINARY REMARKS

Applicant notes that the same rejections and the identical, or virtually identical language in the rejections were employed in the two Office Actions, mailed on March 13, 2003 and August 13, 2002.

The Office provided definitions without citing all sources drawn upon. The recently cited source, <http://www.maxmon.com/et.htm> is unacceptable and should be withdrawn. As noted in a previous response, the definition is clumsy, not academic, and unprofessional.

trace-a conducting connection between electronic components. May also be called a track or a signal. In the case of integrated circuits, such interconnections are often referred to collectively as metallization.

Applicants note this definition refers to a trace in the singular, "a conducting connection". Next the definition lacks an antecedent for the following term, in the plural, "such interconnections are often referred to collectively as metallization." This definition suffers from a disconnect between the singular term "a connection" and the plural term "such interconnections". But without further information, Applicants respectfully assert that the definition provided by the Office, defines a trace as a connection in the singular, and metallization as a collection of "traces," "such interconnections" (ibid.) in the plural. Because Applicants teach and claim a trace, and the cited reference teaches only "metallization", withdrawal of the rejections is respectfully requested.